

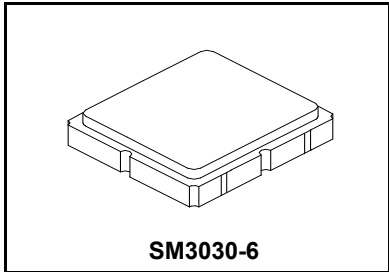


- Low Loss RF SAW Filter
- Surface Mount 3.0 x 3.0 mm Package
- Complies with Directive 2011/65/EU (RoHS)
- Moisture Sensitivity Level: 1

RoHS
Compliant

SF2294E

922.5 MHz
SAW Filter



Absolute Maximum Ratings

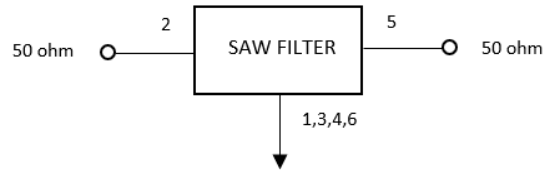
Rating	Value	Units
Input Power Level	13	dBm
DC Voltage on any Non-ground Terminal	5	V
Operable Temperature Range	-45 to +125	°C
Operating Temperature Range	-40 to +85	°C
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Suitable for Lead-free Soldering - Maximum Soldering Profile	260°C for 30 s	

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	f_c			922.5		MHz
Insertion Loss, 920.0 to 925.0 MHz (-20 to +75°C) 920.0 to 925.0 MHz (-40 to +85°C)	IL			2.7	4.2	dB
					4.5	
Amplitude Ripple, 920.0 to 925.0 MHz				0.4	2.0	dB
Attenuation, Referenced to 0 dB:						dB
775 to 835 MHz			40	45		
835 to 895 MHz			36	44		
970 to 992 MHz			36	44		
992 to 1075 MHz			38	45		
Source Impedance	Z_S			50		Ω
Load Impedance	Z_L			50		
Case Style	SM3030-6 3.0 x 3.0 mm Nominal Footprint					
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	A46, YWWS					
Standard Reel Quantity	Reel Size 7 Inch					500 Pieces/Reel
	Reel Size 13 Inch					3000 Pieces/Reel

Electrical Connections

Connection	Terminals
Input	2
Output	5
Case Ground	All others



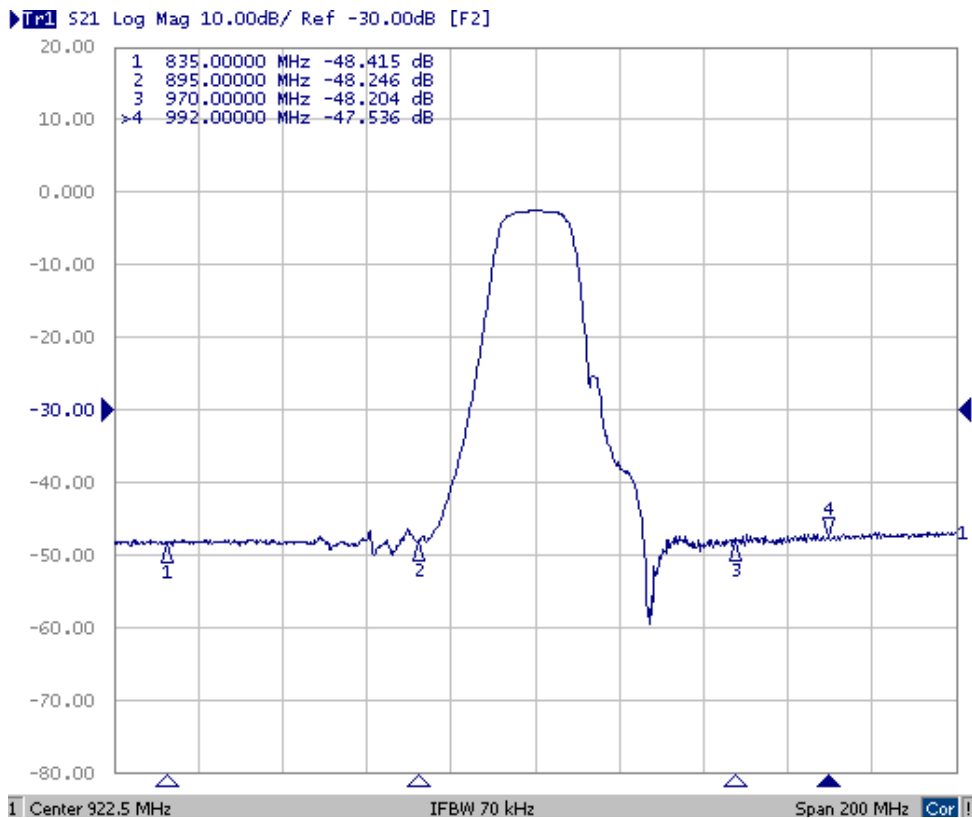
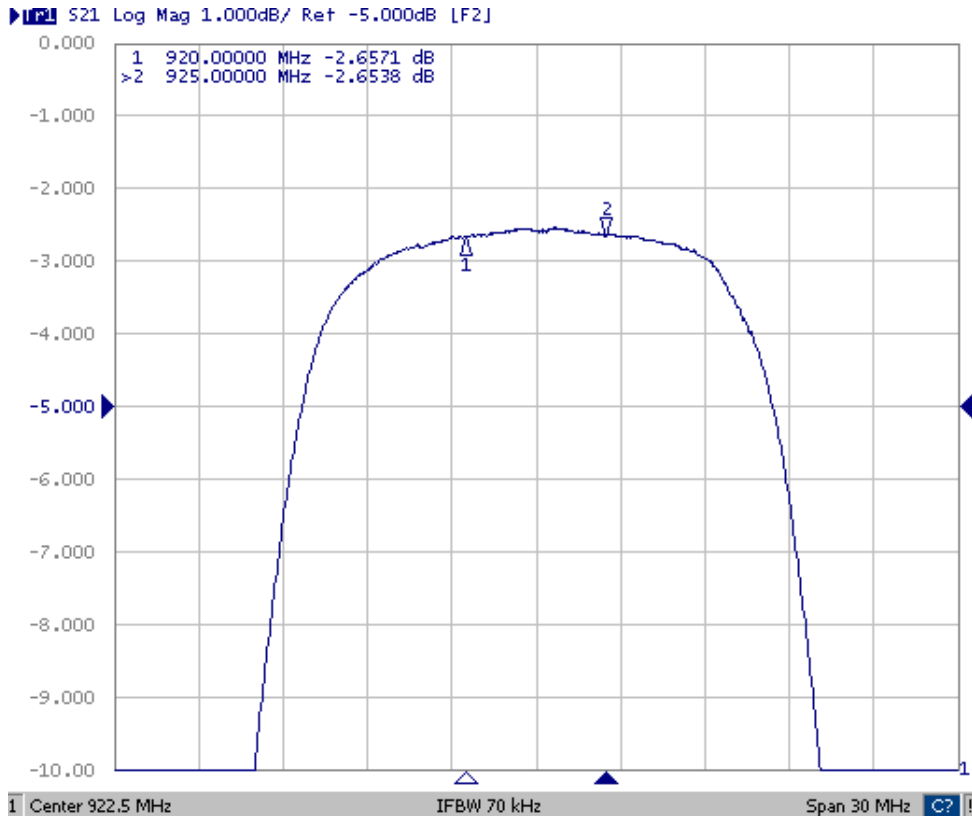
CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.



NOTES:

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

Filter Response Plots



SM3030-6 Case

6-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint



PCB Footprint Top View

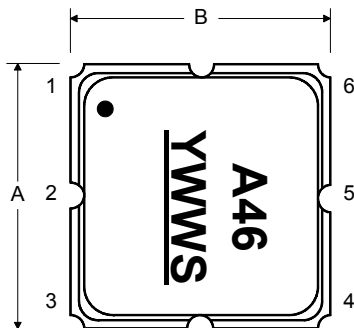
Case and PCB Footprint Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.00	3.13	0.113	0.118	0.123
B	2.87	3.00	3.13	0.113	0.118	0.123
C	1.12	1.25	1.38	0.044	0.049	0.054
D	0.77	0.90	1.03	0.030	0.035	0.040
E	2.67	2.80	2.93	0.105	0.110	0.115
F	1.47	1.60	1.73	0.058	0.063	0.068
G	0.72	0.85	0.98	0.028	0.033	0.038
H	1.37	1.50	1.63	0.054	0.059	0.064
I	0.47	0.60	0.73	0.019	0.024	0.029
J	1.17	1.30	1.43	0.046	0.051	0.056
K		3.20			0.126	
L		1.70			0.067	
M		1.05			0.041	
N		0.81			0.032	
O		0.38			0.015	

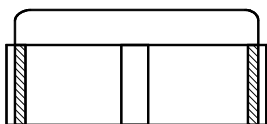
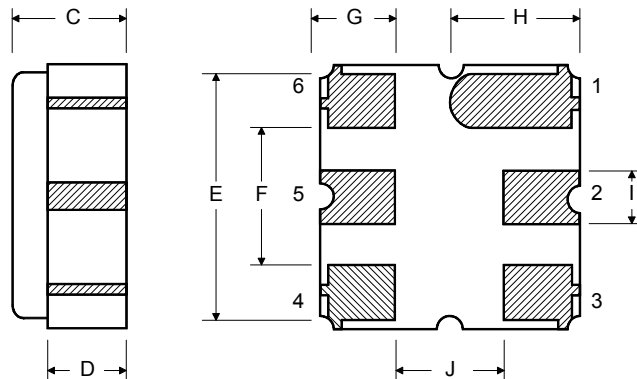
Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 μm Gold over 1.27 to 8.89 μm Nickel
Lid Plating	2.0 to 3.0 μm Nickel
Body	Al_2O_3 Ceramic

TOP VIEW



BOTTOM VIEW



Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
4. Time: 5 times maximum.

